

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Jevan's

In re Application of: Hawks, et al.

Serial No.: 09/638,172

Filed: August 11, 2000

For: "Method and Structure for Securing a Mold Compound to a Printed Circuit Board"

Art Unit: 2831

Examiner: Hung V. Ngo

AMENDMENT AND RESPONSE

Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

Dear Sir/Madam:

This is in response to the Office Action dated July 2, 2001 in the above-referenced patent application. Please enter and consider the following amendments and remarks.

In the Claims:

Please cancel claims 1-10.

RECEIVELL.
JUL 13 2001
TO 2800 MAIL ROOM